

# Chip Scale Review®

ChipScaleReview.com

The Future of Semiconductor Packaging

## 2018 Editorial Calendar

(Editorial close date: 6/15)

July • August

\* indicates show distribution

High reliability materials

Metal-based wafer-level and 3D printed packaging

Temporary bonding for high temperature processing of thin glass

Chip-package-board co-design

Coaxial socket technology

Testing RF devices

Large-area fan-out processing

### • ICEPT 2018

Shanghai, China (Aug 8-11)

### • SEMICON Taiwan \*

Taipei, Taiwan (Sept 5-7)

### • European MEMS & Sensors Summit

Grenoble, France (Sept 19-21)

### • European Imaging & Sensors Summit

Grenoble, France (Sept 19-21)

### • Strategic Materials Conference - SMC

San Jose, CA (Sept 24-26)

International Directory of Wafer Probers & Probe Cards

Ad Space Close Jun 30 - Ad Materials Close Jul 7

(Editorial close date: 7/20)

September • October

\* indicates show distribution

Effective, Scalable EMI Protection

Embedded RDL

High density flip-chip and advanced CSP

High-resolution 3D X-ray metrology

Advanced substrates and embedded packaging

High density advanced packaging (HDAP) design

Direct-placement process for LED's

Inspection strategies

High density advanced packaging design

### • SMTA International \*

Rosemont, IL (October 16-17)

### • IWLP-International Wafer-Level

Packaging Conference & Exhibition \*

San Jose, CA (Oct 23-25)

### • TestConX China 2018

Suzhou, China (Oct 23)

Shenzhen, China (Oct 25)

### • MEMS & Sensors Executive Congress)

San Jose, CA (Oct 28-30)

### • International Test Conference (ITC)

Phoenix, AZ (Oct 31- Nov 2)

### • SEMI International Technology

Partners Conference (ITPC)

Maui, Hawaii (Nov 4-7)

### • SEMICON Europa

Munich, Germany (Nov 13-16)

International Directory of Defect Inspection Systems

Ad Space Close Sep 8 - Ad Materials Close Sep 15

(Editorial close date: 9/21)

November • December

\* indicates show distribution

5G developments

Cooling solutions for hi-density chips

Burn-in system technology advancements

Advanced eWLB for mmWave applications

Package assembly design Kits

Collective bonding for heterogeneous integration

Lithography

Photonics for next generation applications

Robust interconnects for MEMS sensors

Wafer bumping

### • EPTC 2018 \*

Singapore (Dec 4-7)

### • SEMICON Japan

Tokyo, Japan (Dec 12-14)

### • SEMI European 3D Summit \*

Dresden, Germany (Jan 22-24, 2019)

### • SEMICON Korea

Coex, Seoul, Korea (Jan 23-25, 2019)

Ad Space Close Nov 3 - Materials Close Nov 10

For ad inquiries: [ads@chipscalereview.com](mailto:ads@chipscalereview.com) - For editorial inquiries [editor@chipscalereview.com](mailto:editor@chipscalereview.com)

Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.

Haley Publishing Inc.2018 All rights reserved. Rev:CSR-EC-081518